

ECN#	ISS.	REV	DESCRIPTION	DATE	INT.	PG#
.	1	A	INITIAL RELEASE	08-26-16	S	XXX
.	1	B		02-16-17	S	XYZ
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NOTES

MATERIAL: FR4 2 OZ COPPER EACH LAYER, 4 LAYER CONSTRUCTION,
FINAL THICKNESS .063. UNLESS OTHERWISE SPECIFIED ALL
HOLES PLATED THRU WITH COPPER 1 OZ MINIMUM.
FINAL COPPER ON EXTERNAL LAYERS = 2 OZ MINIMUM.
FINISH: SOLDER MASK OVER BARE COPPER, 3-8u" IMMERSION GOLD OVER
100-150u" ELECTROLESS NICKEL ON EXPOSED COPPER.
CHARACTER SCREEN: SCREEN BOTH SIDES OF BOARD USING
WHITE SOLVENT PROOF EPOXY BASE INK.
SOLDER MASK: LIQUID PHOTOIMAGEABLE TWO SIDES.
TOP SIDE: RED, BOTTOM SIDE: BLACK
MATERIAL AND FINISH TO BE ROHS COMPLIANT. Tg=170 Deg. C

SIZE	QTY	SYM	PLATED	TOL
8	3	⊕ ^A	YES	+/-3.0
10	10	⊗	YES	+/-3.0
20	313	⊕	YES	+/-3.0
24	12	□	YES	+/-3.0
38	26	◇	YES	+/-3.0
70.87	5	⊕ ^B	YES	+/-3.0
125.98	4	⊗	NO	+/-2.0
209	4	⊕ ^C	YES	+/-3.0
21.65	2	⊕ ^D	YES	+/-3.0

		Intel® ENPIRION ® Power Solutions			
DRAWN BY		DATE		EN6340 ENG. Board	
Wei/Sorin		02-16-2017			
UNLESS OTHERWISE SPECIFIED TOLERANCES: .XX +/- .020 .XXX +/- .010 ANG. +/- 1 DEG.		FAB			
		SIZE	ISSUE	REV.	DRAWING NO.
		A	1	C	.
		SCALE: 1		SHEET: 1 OF 1	

